

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Thomas H. Ivers et al.

Serial No.: 09/231,618 : Art Unit: 2823

Filed: January 14, 1999 : Examiner: Collins, D.

For: Method for Improving  
Adhesion to Copper : Atty Docket: FI9-98-172

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**SUBMISSION OF FORMAL DRAWINGS**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicants submit herewith 1 sheet of formal drawings of Figs. 1-3.

Respectfully submitted,

  
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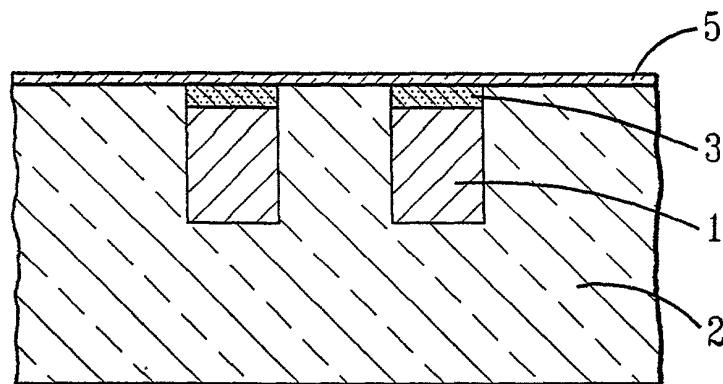


FIG. 1

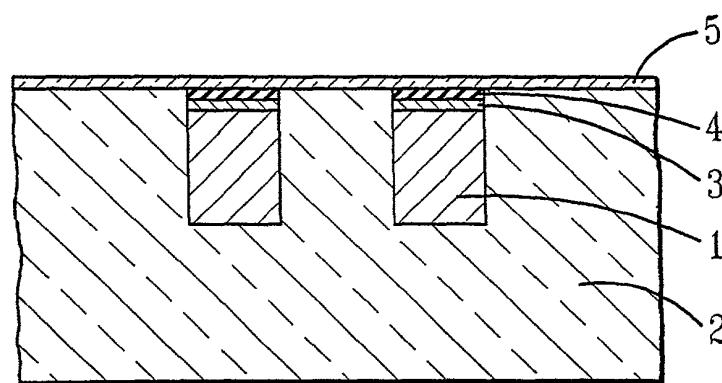


FIG. 2

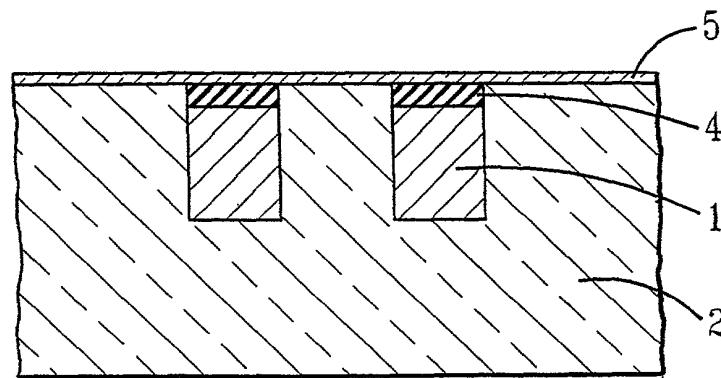


FIG. 3